

| | Hits | Search Text | DBs |
|----|------|---|---|
| 43 | 1 | ((heat\$4 or anneal\$4 or bak\$4) same (top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (reflow\$4 or (glass near9 transit\$5)) same (substrate or wafer) same pressure) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist)) and (exposure or irradiat\$\$) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 44 | 61 | ((heat\$4 or anneal\$4 or bak\$4) same (top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (reflow\$4 or (glass near9 transit\$5)) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist)) and (exposure or irradiat\$\$) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |
| 45 | 1 | ((heat\$4 or anneal\$4 or bak\$4) same (top or upper or front) same (bottom or lower or (substrate near5 holder) or hold\$4 or stage) same (resist or photoresist) same (reflow\$4 or (glass near9 transit\$5)) same (substrate or wafer)) and develop\$4 and ((coat\$4 or form\$4) same (resist or photoresist)) and (exposure or irradiat\$\$) and ((heat\$4 or bak\$4 or anneal\$4 or PEB or (post near9 bak\$4)) same (substrate or wafer or workpiece) same (photoresist or resist or photocur\$4 or polyimide) same pressure same control\$4) | US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB |